L Number	Hits	Search Text	DB	Time stamp
10	90	(low near solder) and (high near solder) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:56
11	0	6344234.URPN.	USPAT	2002/11/13 11:50
12	0	6344234.URPN.	USPAT	2002/11/13 11:50
13	12	("3458925" | "3512051" | "4536421" | "4673772" | "4739917" | "4830723" | "4950623" | "4967950" | "5075965" | "5130779" | "5154341" | "5251806").PN.	USPAT	2002/11/13 11:50
14	39	5251806.URPN.	USPAT	2002/11/13 11:54
15	30	5641113.URPN.	USPAT	2002/11/13 12:00
16	30	5641113.URPN.	USPAT	2002/11/13 12:02
17	30	5641113.URPN.	USPAT	2002/11/13 12:04
20	17	438/690.ccls.and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:31
21	179	abrad$3 same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:52
22	3	((low near point) and (high near point)) and (barrier near solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:54
23	10	5536362.URPN.	USPAT	2002/11/13 12:55
24	2	(low near solder) and (high near solder) and (solder near barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 13:02
25	1	((low near solder) and (high near solder)) same barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 13:03
26	1	("4679772").PN.	USPAT	2002/11/13 13:03
27	1	("4673772").PN.	USPAT	2002/11/13 13:04
28	61	ball near barrier	USPAT	2002/11/13 13:05
29	121	solder near barrier	USPAT	2002/11/13 13:05
30	1	(ball near barrier) and (solder near barrier)	USPAT	2002/11/13 13:05
31	181	(ball near barrier) or (solder near barrier)	USPAT	2002/11/13 13:06
32	112	((ball near barrier) or (solder near barrier)) and (substrate or chip or die)	USPAT	2002/11/13 13:10
33	245955	dual solder	USPAT	2002/11/13 13:11
34	16	dual adj solder	USPAT	2002/11/13 13:12
35	0	257/780.ccls. and barrer	USPAT	2002/11/13 13:13
36	91	257/780.ccls. and barrer	USPAT	2002/11/13 13:14